Microchip Technology - SST89E516RD2-40-I-TQJE-NXX Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	40MHz
Connectivity	EBI/EMI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	36
Program Memory Size	72KB (72K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/sst89e516rd2-40-i-tqje-nxx

Product Description

The SST89E516RDx and SST89V516RDx are members of the FlashFlex family of 8-bit microcontroller products designed and manufactured with SST's patented and proprietary SuperFlash CMOS semiconductor process technology. The split-gate cell design and thick-oxide tunneling injector offer significant cost and reliability benefits for SST's customers. The devices use the 8051 instruction set and are pin-for-pin compatible with standard 8051 microcontroller devices.

The devices come with 72 KByte of on-chip flash EEPROM program memory which is partitioned into 2 independent program memory blocks. The primary Block 0 occupies 64 KByte of internal program memory space and the secondary Block 1 occupies 8 KByte of internal program memory space.

The 8-KByte secondary block can be mapped to the lowest location of the 64 KByte address space; it can also be hidden from the program counter and used as an independent EEPROM-like data memory.

In addition to the 72 KByte of EEPROM program memory on-chip and 1024 x8 bits of on-chip RAM, the devices can address up to 64 KByte of external program memory and up to 64 KByte of external RAM.

The flash memory blocks can be programmed via a standard 87C5x OTP EPROM programmer fitted with a special adapter and the firmware for SST's devices. During power-on reset, the devices can be configured as either a slave to an external host for source code storage or a master to an external host for an in-application programming (IAP) operation. The devices are designed to be programmed in-system and in-application on the printed circuit board for maximum flexibility. The devices are pre-programmed with an example of the bootstrap loader in the memory, demonstrating the initial user program code loading or subsequent user code updating via the IAP operation. The sample bootstrap loader is available for the user's reference and convenience only; SST does not guarantee its functionality or usefulness. Chip-Erase or Block-Erase operations will erase the pre-programmed sample code.

Memory Organization

The device has separate address spaces for program and data memory.

Program Flash Memory

There are two internal flash memory blocks in the device. The primary flash memory block (Block 0) has 64 KByte. The secondary flash memory block (Block 1) has 8 KByte. Since the total program address space is limited to 64 KByte, the SFCF[1:0] bit are used to control program bank selection. Please refer to Figure 6 for the program memory configuration. Program bank selection is described in the next section.

The 64K x8 primary SuperFlash block is organized as 512 sectors, each sector consists of 128 Bytes.

The 8K x8 secondary SuperFlash block is organized as 64 sectors, each sector consists also of 128 Bytes.

For both blocks, the 7 least significant program address bits select the byte within the sector. The remainder of the program address bits select the sector within the block.

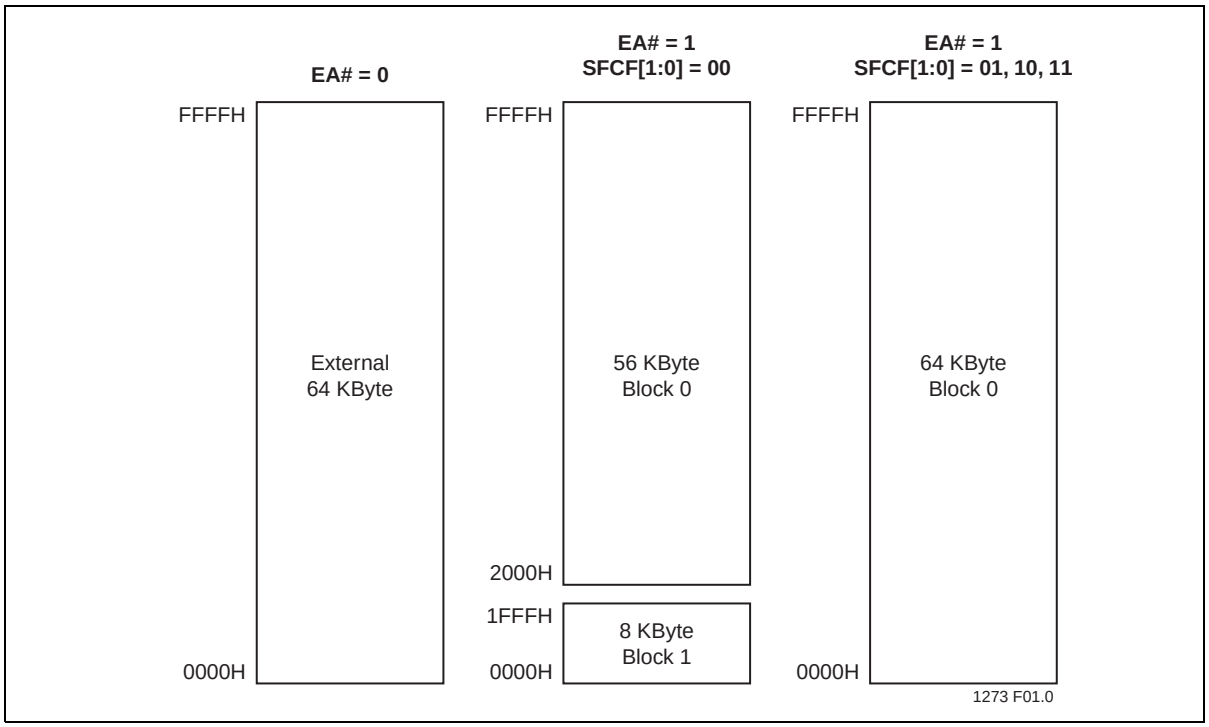

Figure 6: Program Memory Organization

Program Memory Block Switching

The program memory block switching feature of the device allows either Block 1 or the lowest 8 KByte of Block 0 to be used for the lowest 8 KByte of the program address space. SFCF[1:0] controls program memory block switching.

Table 2: SFCF Values for Program Memory Block Switching

SFCF[1:0]	Program Memory Block Switching
01, 10, 11	Block 1 is not visible to the program counter (PC). Block 1 is reachable only via in-application programming from 0000H - 1FFFH.
00	Block 1 is overlaid onto the low 8K of the program address space; occupying address locations 0000H - 1FFFH. When the PC falls within 0000H - 1FFFH, the instruction will be fetched from Block 1 instead of Block 0. Outside of 0000H - 1FFFH, Block 0 is used. Locations 0000H - 1FFFH of Block 0 are reachable through in-application programming.

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Reset Configuration of Program Memory Block Switching

Program memory block switching is initialized after reset according to the state of the Start-up Configuration bit SC0. The SC0 bit is programmed via an external host mode command or an IAP Mode command. See Table 14.

Once out of reset, the SFCF[0] bit can be changed dynamically by the program for desired effects. Changing SFCF[0] will not change the SC0 bit.

Caution must be taken when dynamically changing the SFCF[0] bit. Since this will cause different physical memory to be mapped to the logical program address space. The user must avoid executing block switching instructions within the address range 0000H to 1FFFH.

Table 3: SFCF Values Under Different Reset Conditions

	State of SFCF[1:0] after:		
SC0[1]	Power-on or External Reset	WDT Reset or Brown-out Reset	Software Reset
U (1)	00 (default)	x0	10
P (0)	01	x1	11

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1. P = Programmed (Bit logic state = 0),
   U = Unprogrammed (Bit logic state = 1)

Data RAM Memory

The data RAM has 1024 bytes of internal memory. The RAM can be addressed up to 64KB for external data memory.

high-order eight address bits (DPH), and Port 0 multiplexes the low order eight address bits (DPL) with data. Both MOVX @Ri and MOVX @DPTR generates the necessary read and write signals (P3.6 - WR# and P3.7 - RD#) for external memory use. Table 4 shows external data memory RD#, WR# operation with EXTRAM bit.

The stack pointer (SP) can be located anywhere within the 256 bytes of internal RAM (lower 128 bytes and upper 128 bytes). The stack pointer may not be located in any part of the expanded RAM.

Table 4: External Data Memory RD#, WR# with EXTRAM bit

	MOVX @DPTR, A or MOVX A, @DPTR		MOVX @Ri, A or MOVX A, @Ri
AUXR	**ADDR < 0300H**	**ADDR >= 0300H**	**ADDR = Any**
EXTRAM = 0	RD# / WR# not asserted	RD# / WR# asserted	RD# / WR# not asserted[1]
EXTRAM = 1	RD# / WR# asserted	RD# / WR# asserted	RD# / WR# asserted

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1. Access limited to ERAM address within 0 to 0FFH; cannot access 100H to 02FFH.

Table 10: Interface SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	RESET Value
SBUF	Serial Data Buffer	99H	SBUF[7:0]								Indeterminate
SCON[1]	Serial Port Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SADDR	Slave Address	A9H	SADDR[7:0]								00H
SADEN	Slave Address Mask	B9H	SADEN[7:0]								00H
SPCR	SPI Control Register	D5H	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04H
SPSR	SPI Status Register	AAH	SPIF	WCOL							00H
SPDR	SPI Data Register	86H	SPDR[7:0]								00H
P0[1]	Port 0	80H	P0[7:0]								FFH
P1[1]	Port 1	90H	-	-	-	-	-	-	T2EX	T2	FFH
P2[1]	Port 2	A0H	P2[7:0]								FFH
P3[1]	Port 3	B0H	RD#	WR#	T1	T0	INT1#	INT0#	TXD	RXD	FFH
P4[2]	Port 4	A5H	1	1	1	1	P4.3	P4.2	P4.1	P4.0	FFH

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1. Bit Addressable SFRs
2. P4 is similar to P1 and P3 ports

Table 11: PCA SFRs

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB							LSB	RESET Value
CH CL	PCA Timer/Counter	F9H E9H	CH[7:0] CL[7:0]								00H 00H
CCON[1]	PCA Timer/Counter Control Register	D8H	CF	CR	-	CCF4	CCF3	CCF2	CCF1	CCF0	00x0000 0b
CMOD	PCA Timer/Counter Mode Register	D9H	CIDL	WDTE	-	-	-	CPS1	CPS0	ECF	00xxx000 b
CCAP0H	PCA Module 0 Compare/Capture Registers	FAH	CCAP0H[7:0]								00H
CCAP0L		EAH	CCAP0L[7:0]								00H
CCAP1H	PCA Module 1 Compare/Capture Registers	FBH	CCAP1H[7:0]								00H
CCAP1L		EBH	CCAP1L[7:0]								00H
CCAP2H	PCA Module 2 Compare/Capture Registers	FCH	CCAP2H[7:0]								00H
CCAP2L		ECH	CCAP2L[7:0]								00H
CCAP3H	PCA Module 3 Compare/Capture Registers	FDH	CCAP3H[7:0]								00H
CCAP3L		EDH	CCAP3L[7:0]								00H
CCAP4H	PCA Module 4 Compare/Capture Registers	FEH	CCAP4H[7:0]								00H
CCAP4L		EEH	CCAP4L[7:0]								00H
CCAPM0	PCA Compare/Capture Module Mode Registers	DAH	-	ECOM0	CAPP0	CAPN0	MAT0	TOG0	PWM0	ECCF0	x000000 0b
CCAPM1		DBH	-	ECOM1	CAPP1	CAPN1	MAT1	TOG1	PWM1	ECCF1	x000000 0b
CCAPM2		DCH	-	ECOM2	CAPP2	CAPN2	MAT2	TOG2	PWM2	ECCF2	x000000 0b
CCAPM3		DDH	-	ECOM3	CAPP3	CAPN3	MAT3	TOG3	PWM3	ECCF3	x000000 0b
CCAPM4		DEH	-	ECOM4	CAPP4	CAPN4	MAT4	TOG4	PWM4	ECCF4	x000000 0b

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1. Bit Addressable SFRs

SuperFlash Configuration Register (SFCF)

Location	7	6	5	4	3	2	1	0	Reset Value
B1H	-	IAPEN	-	-	-	-	SWR	BSEL	x0xxxx00b

Symbol	Function
IAPEN	Enable IAP operation 0: IAP commands are disabled 1: IAP commands are enabled
SWR	Software Reset See Section , “Software Reset”
BSEL	Program memory block switching bit See Figure 6 and Table 3

SuperFlash Command Register (SFCM)

Location	7	6	5	4	3	2	1	0	Reset Value
B2H	FIE	FCM6	FCM5	FCM4	FCM3	FCM2	FCM1	FCM0	00H

Symbol	Function
FIE	Flash Interrupt Enable. 0: INT1# is not reassigned. 1: INT1# is re-assigned to signal IAP operation completion. External INT1# interrupts are ignored.
FCM[6:0]	Flash operation command 000_0001b Chip-Erase 000_1011b Sector-Erase 000_1101b Block-Erase 000_1100b Byte-Verify[1] 000_1110b Byte-Program 000_1111b Prog-SB1 000_0011b Prog-SB2 000_0101b Prog-SB3 000_1001b Prog-SC0 000_1000bEnable-Clock-Double All other combinations are not implemented, and reserved for future use.

1. Byte-Verify has a single machine cycle latency and will not generate any INT1# interrupt regardless of FIE.

SuperFlash Address Registers (SFAL)

Location	7	6	5	4	3	2	1	0	Reset Value
B3H	SuperFlash Low Order Byte Address Register								00H

Symbol	Function
SFAL	Mailbox register for interfacing with flash memory block. (Low order address register).

Interrupt Enable (IE)

Location	7	6	5	4	3	2	1	0	Reset Value
A8H	EA	EC	ET2	ES	ET1	EX1	ET0	EX0	00H

Symbol	Function
EA	Global Interrupt Enable. 0 = Disable 1 = Enable
EC	PCA Interrupt Enable.
ET2	Timer 2 Interrupt Enable.
ES	Serial Interrupt Enable.
ET1	Timer 1 Interrupt Enable.
EX1	External 1 Interrupt Enable.
ET0	Timer 0 Interrupt Enable.
EX0	External 0 Interrupt Enable.

Interrupt Enable A (IEA)

Location	7	6	5	4	3	2	1	0	Reset Value
E8H	-	-	-	-	EBO	-	-	-	xxxx0xxxb

Symbol	Function
EBO	Brown-out Interrupt Enable. 1 = Enable the interrupt 0 = Disable the interrupt

Flash Memory Programming

The device internal flash memory can be programmed or erased using In-Application Programming (IAP) mode

Product Identification

The Read-ID command accesses the Signature Bytes that identify the device and the manufacturer as SST. External programmers primarily use these Signature Bytes in the selection of programming algorithms.

Table 12: Product Identification

	Address	Data
Manufacturer's ID	30H	BFH
Device ID		
SST89E516RD2/RD	31H	93H
SST89V516RD2/RD	31H	92H

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In-Application Programming Mode

The device offers either 72 KByte of in-application programmable flash memory. During in-application programming, the CPU of the microcontroller enters IAP mode. The two blocks of flash memory allow the CPU to execute user code from one block, while the other is being erased or reprogrammed concurrently. The CPU may also fetch code from an external memory while all internal flash is being reprogrammed. The mailbox registers (SFST, SFCM, SFAL, SFAH, SFDT and SFCF) located in the special function register (SFR), control and monitor the device's erase and program process.

Table 14 outline the commands and their associated mailbox register settings.

In-Application Programming Mode Clock Source

During IAP mode, both the CPU core and the flash controller unit are driven off the external clock. However, an internal oscillator will provide timing references for Program and Erase operations. The internal oscillator is only turned on when required, and is turned off as soon as the flash operation is completed.

Memory Bank Selection for In-Application Programming Mode

With the addressing range limited to 16 bit, only 64 KByte of program address space is "visible" at any one time. As shown in Table 13, the bank selection (the configuration of EA# and SFCF[1:0]), allows Block 1 memory to be overlaid on the lowest 8 KByte of Block 0 memory, making Block 1 reachable. The same concept is employed to allow both Block 0 and Block 1 flash to be accessible to IAP operations. Code from a block that is not visible may not be used as a source to program another address. However, a block that is not "visible" may be programmed by code from the other block through mailbox registers.

The device allows IAP code in one block of memory to program the other block of memory, but may not program any location in the same block. If an IAP operation originates physically from Block 0, the target of this operation is implicitly defined to be in Block 1. If the IAP operation originates physically from

Byte-Verify

The Byte-Verify command allows the user to verify that the device has correctly performed an Erase or Program command. Byte-Verify command returns the data byte in SFDT if the command is successful. The user is required to check that the previous flash operation has fully completed before issuing a Byte-Verify. Byte-Verify command execution time is short enough that there is no need to poll for command completion and no interrupt is generated.

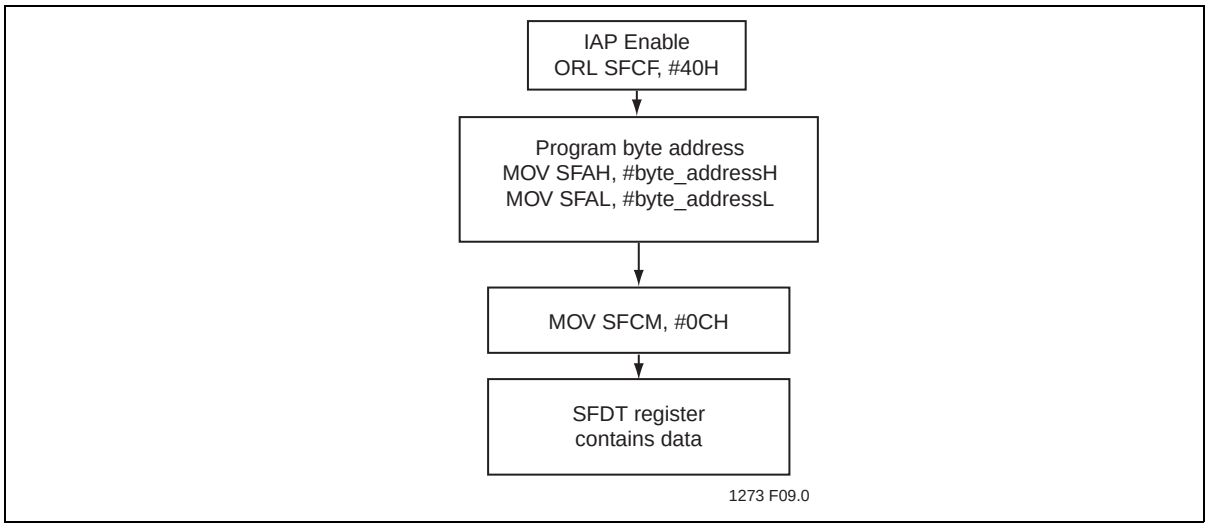

Figure 13: Byte Verify

Prog-SB3, Prog-SB2, Prog-SB1

Prog-SB3, Prog-SB2, Prog-SB1 commands are used to program the security bits (see Table 25). Completion of any of these commands, the security options will be updated immediately.

Security bits previously in un-programmed state can be programmed by these commands. Prog-SB3, Prog-SB2 and Prog-SB1 commands should only reside in Block 1 or external code memory.

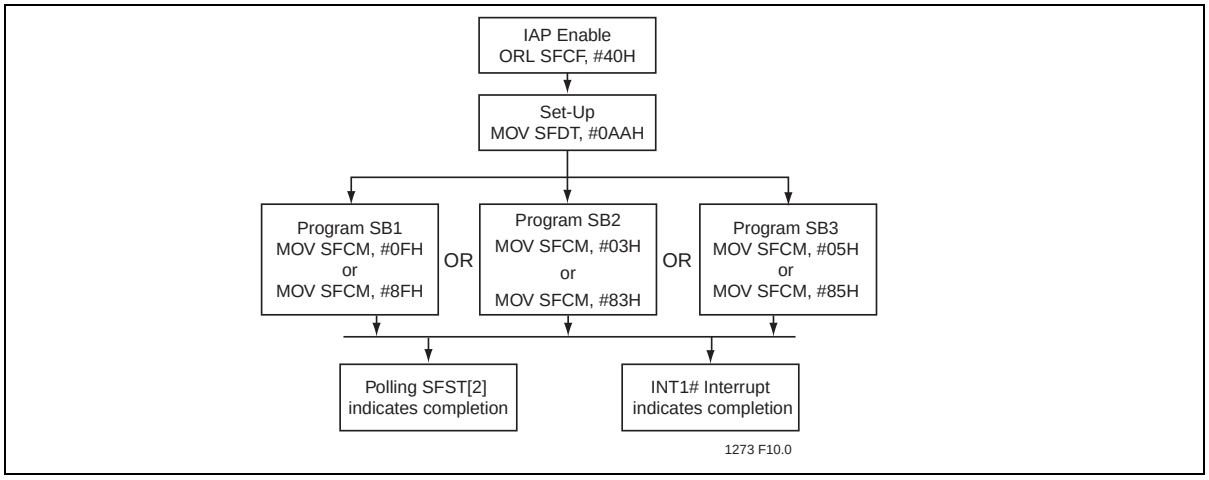

Figure 14: Prog-SB3, Prog-SB2, Prog-SB1

Prog-SC0

Prog-SC0 command is used to program the SC0 bit. This command only changes the SC0 bit and has no effect on BSEL bit until after a reset cycle.

SC0 bit previously in un-programmed state can be programmed by this command. The Prog-SC0 command should reside only in Block 1 or external code memory.

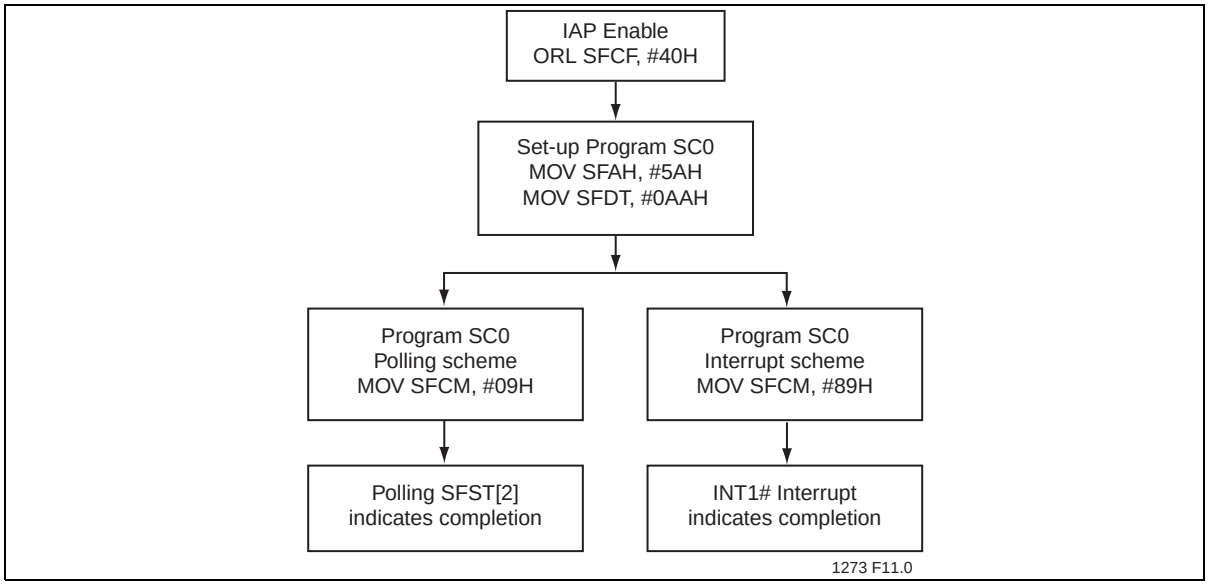

Figure 15: Prog-SC0

Enable-Clock-Double

Enable-Clock-Double command is used to make the MCU run at 6 clocks per machine cycle. The standard (default) is 12 clocks per machine cycle (i.e. clock double command disabled).

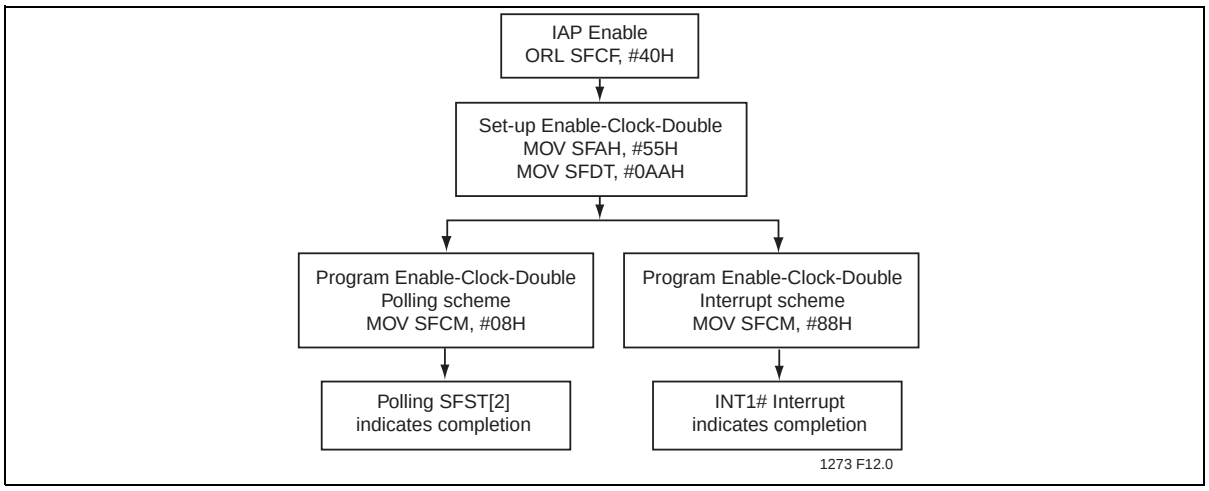

Figure 16: Enable-Clock-Double

There are no IAP counterparts for the external host commands Select-Block0 and Select-Block1.

Polling

A command that uses the polling method to detect flash operation completion should poll on the FLASH_BUSY bit (SFST[2]). When FLASH_BUSY de-asserts (logic 0), the device is ready for the next operation.

MOVC instruction may also be used for verification of the Programming and Erase operation of the flash memory. MOVC instruction will fail if it is directed at a flash block that is still busy.

Interrupt Termination

If interrupt termination is selected, (SFCM[7] is set), then an interrupt (INT1) will be generated to indicate flash operation completion. Under this condition, the INT1 becomes an internal interrupt source. The INT1# pin can now be used as a general purpose port pin and it cannot be the source of External Interrupt 1 during in-application programming.

In order to use an interrupt to signal flash operation termination. EX1 and EA bits of IE register must be set. The IT1 bit of TCON register must also be set for edge trigger detection.

Table 14: IAP Commands[1]

Operation	SFCM [6:0][2]	SFDT [7:0]	SFAH [7:0]	SFAL [7:0]
Chip-Erase[3]	01H	55H	X[4]	X
Block-Erase[5]	0DH	55H	AH	X
Sector-Erase[5]	0BH	X	AH[6]	AL[7]
Byte-Program[5]	0EH	DI[8]	AH	AL
Byte-Verify (Read)[5]	0CH	DO[8]	AH	AL
Prog-SB1[9]	0FH	AAH	X	X
Prog-SB2[9]	03H	AAH	X	X
Prog-SB3[9]	05H	AAH	X	X
Prog-SC0[9]	09H	AAH	5AH	X
Enable-Clock-Double[9]	08H	AAH	55H	X

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1. SFCF[6]=1 enables IAP commands; SFCF[6]=0 disables IAP commands.
2. Interrupt/Polling enable for flash operation completion
   SFCM[7] =1: Interrupt enable for flash operation completion
   0: polling enable for flash operation completion
3. Chip-Erase only functions in IAP mode when EA#=0 (external memory execution) and device is not in level 4 locking.
4. X can be V_{IL} or V_{IH}, but no other value.
5. Refer to Table 13 for address resolution
6. AH = Address high order byte
7. AL = Address low order byte
8. DI = Data Input, DO = Data Output, all other values are in hex.
9. Instruction must be located in Block 1 or external code memory.

Note: DISIAPL pin in PLCC or TQFP will also disable IAP commands if it is externally pulled low when reset.

an interrupt will be generated if the ECF bit in the CMOD register is set. The CF bit can only be cleared by software. Each module has its own timer interrupt or capture interrupt flag (CCF0 for module 0, CCF4 for module 4, etc.). They are set when either a match or capture occurs. These flags can only be cleared by software. (See “PCA Timer/Counter Control Register (CCON)” on page 27.)

Compare/Capture Modules

Each PCA module has an associated SFR with it. These registers are: CCAPM0 for module 0, CCAPM1 for module 1, etc. Refer to “PCA Compare/Capture Module Mode Register (CCAPMn)” on page 29 for details. The registers each contain 7 bits which are used to control the mode each module will operate in. The ECCF bit (CCAPMn.0 where n = 0, 1, 2, 3, or 4 depending on module) will enable the CCF flag in the CCON SFR to generate an interrupt when a match or compare occurs. PWM (CCAPMn.1) enables the pulse width modulation mode. The TOG bit (CCAPMn.2) when set, causes the CEX output associated with the module to toggle when there is a match between the PCA counter and the module’s capture/compare register. When there is a match between the PCA counter and the module’s capture/compare register, the MATn (CCAPMn.3) and the CCFn bit in the CCON register to be set.

Bits CAPN (CCAPMn.4) and CAPP (CCAPMn.5) determine whether the capture input will be active on a positive edge or negative edge. The CAPN bit enables the negative edge that a capture input will be active on, and the CAPP bit enables the positive edge. When both bits are set, both edges will be enabled and a capture will occur for either transition. The last bit in the register ECOM (CCAPMn.6) when set, enables the comparator function. Table 22 shows the CCAPMn settings for the various PCA functions.

There are two additional register associated with each of the PCA modules: CCAPnH and CCAPnL. They are registers that hold the 16-bit count value when a capture occurs or a compare occurs. When a module is used in PWM mode, these registers are used to control the duty cycle of the output. See Figure 24.

Table 21: PCA High and Low Register Compare/Capture Modules

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function MSB LSB	RESET Value
CCAP0H	PCA Module 0 Compare/Capture Registers	FAH	CCAP0H[7:0]	00H
CCAP0L		EAH	CCAP0L[7:0]	00H
CCAP1H	PCA Module 1 Compare/Capture Registers	FBH	CCAP1H[7:0]	00H
CCAP1L		EBH	CCAP1L[7:0]	00H
CCAP2H	PCA Module 2 Compare/Capture Registers	FCH	CCAP2H[7:0]	00H
CCAP2L		ECH	CCAP2L[7:0]	00H
CCAP3H	PCA Module 3 Compare/Capture Registers	FDH	CCAP3H[7:0]	00H
CCAP3L		EDH	CCAP3L[7:0]	00H
CCAP4H	PCA Module 4 Compare/Capture Registers	FEH	CCAP4H[7:0]	00H
CCAP4L		EEH	CCAP4L[7:0]	00H

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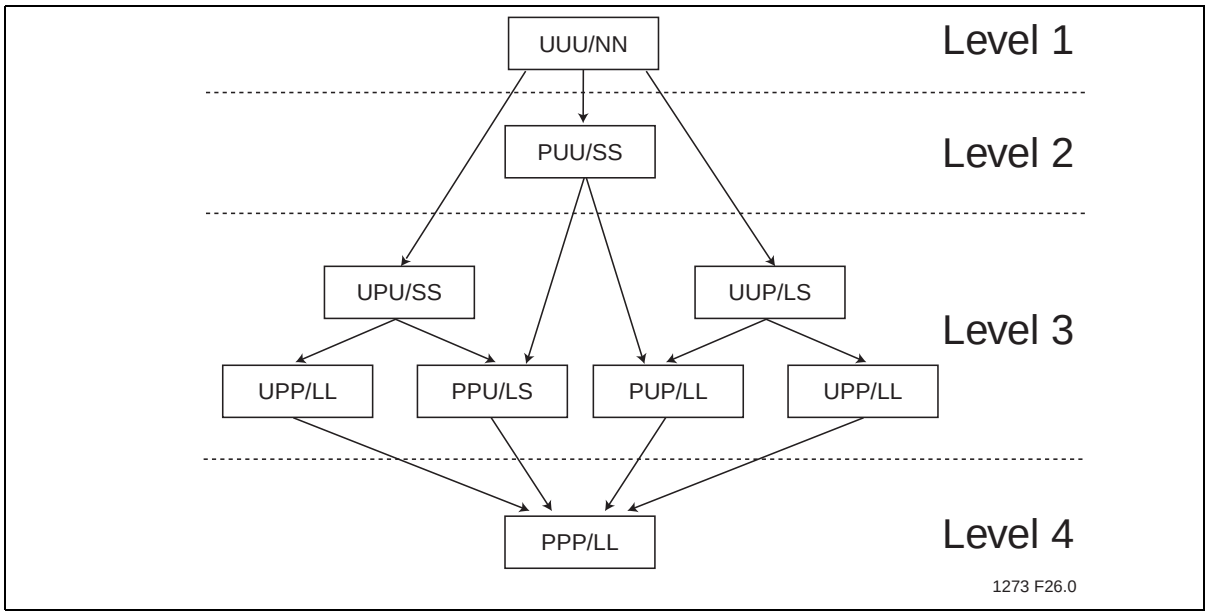

Figure 30: Security Lock Levels

Note: P = Programmed (Bit logic state = 0), U = Unprogrammed (Bit logic state = 1), N = Not Locked, L = Hard locked, S = Soft locked

Table 25: Security Lock Options

Level	Security Lock Bits[1,2]				Security Status of:		Security Type
	SFST[7:5]	SB1	SB2[1]	SB3[1]	Block 1	Block 0	
1	000	U	U	U	Unlock	Unlock	No Security Features are Enabled.
2	100	P	U	U	SoftLock	SoftLock	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, EA# is sampled and latched on Reset, and further programming of the flash is disabled.
3	011 101	U P	P U	P P	Hard Lock	Hard Lock	Level 2 plus Verify disabled, both blocks locked.
	010	U	P	U	SoftLock	SoftLock	Level 2 plus Verify disabled. Code in Block 1 may program Block 0 and vice versa.
	110 001	P U	P U	U P	Hard Lock	SoftLock	Level 2 plus Verify disabled. Code in Block 1 may program Block 0.
4	111	P	P	P	Hard Lock	Hard Lock	Same as Level 3 hard lock/hard lock, but MCU will start code execution from the internal memory regardless of EA#.

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1. P = Programmed (Bit logic state = 0), U = Unprogrammed (Bit logic state = 1).
2. SFST[7:5] = Security Lock Status Bits (SB1_i, SB2_i, SB3_i)

Table 32: Reliability Characteristics

Symbol	Parameter	Minimum Specification	Units	Test Method
N_{END}[1]	Endurance	10,000	Cycles	JEDEC Standard A117
T_{DR}[1]	Data Retention	100	Years	JEDEC Standard A103
I_{LTH}[1]	Latch Up	100 + I_{DD}	mA	JEDEC Standard 78

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1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.

Table 33: AC Conditions of Test[1]

Input Rise/Fall Time	Output Load
10 ns	C_L = 100 pF

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1. See Figures 41 and 43

Table 34: Recommended System Power-up Timings

Symbol	Parameter	Minimum	Units
$T_{PU-READ}$[1]	Power-up to Read Operation	100	µs
$T_{PU-WRITE}$[1]	Power-up to Write Operation	100	µs

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1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter

Table 35: Pin Impedance **(V_{DD}=3.3V, T_A=25°C, f=1 Mhz, other pins open)**

Parameter	Description	Test Condition	Maximum
$C_{I/O}$[1]	I/O Pin Capacitance	$V_{I/O}$ = 0V	15 pF
C_{IN}[1]	Input Capacitance	V_{IN} = 0V	12 pF
L_{PIN}[2]	Pin Inductance		20 nH

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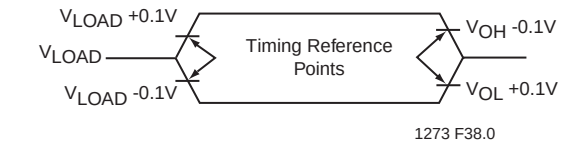
1. This parameter is measured only for initial qualification and after a design or process change that could affect this parameter.
2. Refer to PCI spec.



For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs, and begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs. I_{OL}/I_{OH} = ± 20mA.

Figure 42: Float Waveform

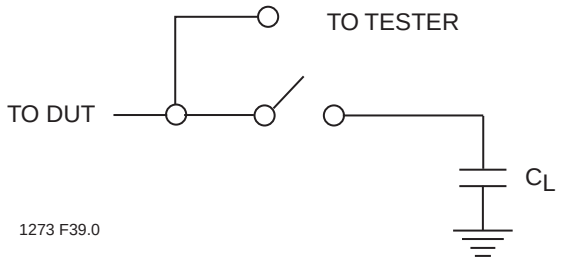
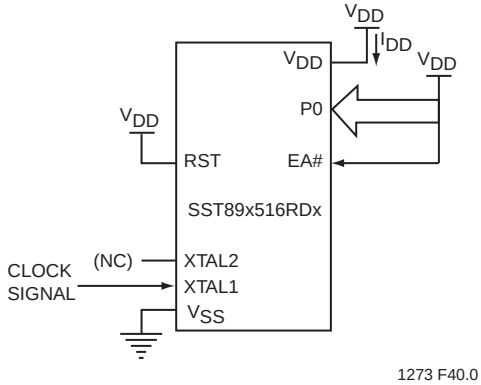


Figure 43: A Test Load Example



All other pins disconnected

Figure 44: I_{DD} Test Condition, Active Mode

Valid Combinations

Valid combinations for SST89E516RD2

SST89E516RD2-40-C-NJE	SST89E516RD2-40-C-TQJE
SST89E516RD2-40-I-NJE	SST89E516RD2-40-I-TQJE

Valid combinations for SST89V516RD2

SST89V516RD2-33-C-NJE	SST89V516RD2-33-C-TQJE
SST89V516RD2-33-I-NJE	SST89V516RD2-33-I-TQJE

Valid combinations for SST89E516RD

SST89E516RD-40-C-PIE	SST89E516RD-40-C-QIF
	SST89E516RD-40-I-QIF

Valid combinations for SST89V516RD

SST89V516RD-33-C-PIE	SST89V516RD-33-C-QIF
	SST89V516RD-33-I-QIF

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.

Packaging Diagrams

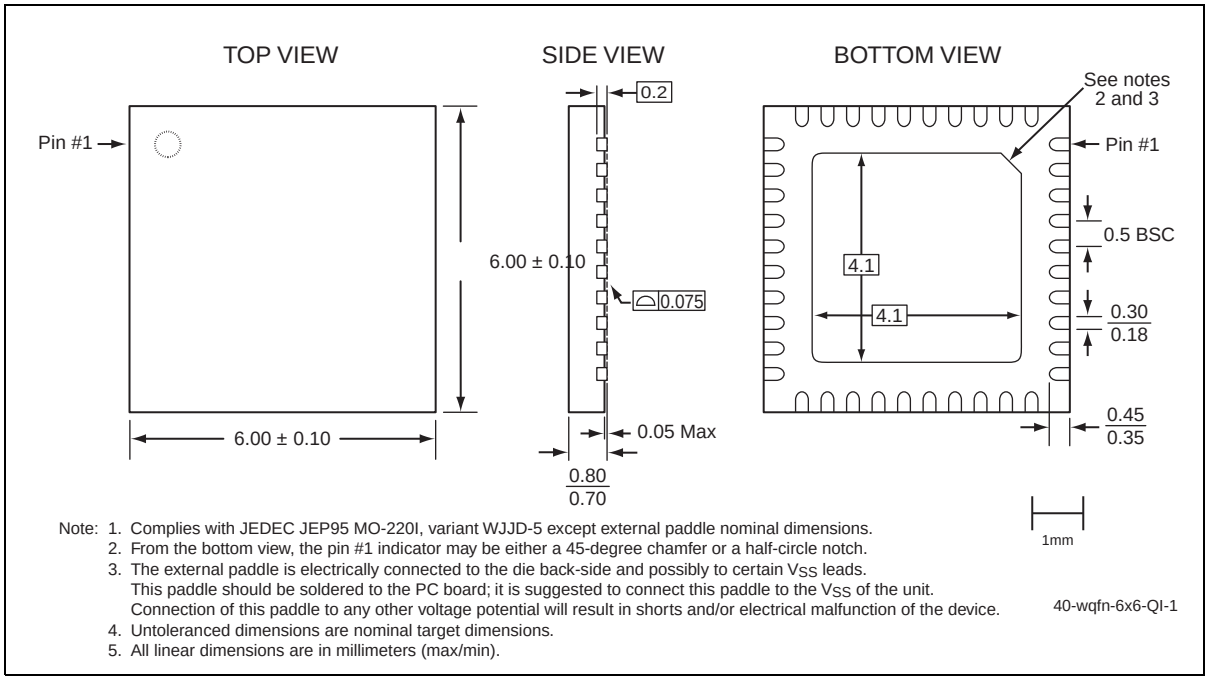
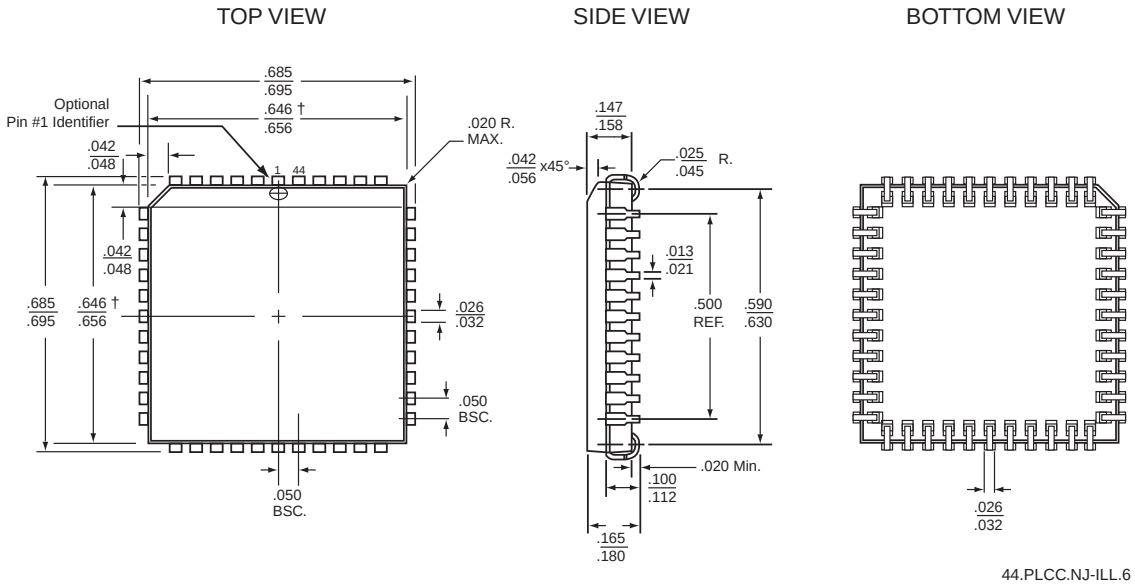


Figure 47: 40-contact Very-very-thin Quad Flat No-lead (WQFN)
SST Package Code: QI



Note:
1. Complies with JEDEC publication 95 MS-018 AC dimensions (except as noted), although some dimensions may be more stringent.
   † = JEDEC min is .650; SST min is *less*stringent
2. All linear dimensions are in inches (min/max).
3. Dimensions do not include mold flash. Maximum allowable mold flash is .008 inches.
4. Coplanarity: ± 4 mils.

Figure 49: 44-lead Plastic Lead Chip Carrier (PLCC)
SST Package Code: NJ

Table 42: Revision History

Revision	Description	Date
00	• Initial Release of S71273 data sheet. SST89E/V516RD2 devices were previously released in S71255-00-000 • S71273 and S71273(01): Added 40-WQFN (QI) package and associated MPNs • Added SST89E/V516RD PDIP devices and associated MPNs • Clarified the solder temperature profile under “Absolute Maximum Stress Ratings” on page 73 • Added RoHS compliance information on page 1 and in the “Product Ordering Information” on page 88 • Removed references to External Host Mode programming • Corrected MPN breakdown definition for “2” to read “Port 4 present” • Corrected the SPI control Register definition for CPHA on page 30	Mar 2005
01	• Status change from Preliminary Specifications to Data sheet	Mar 2005
02	• Removed NJ, TQJ, and PI from Valid Combinations on page 78 • Removed valid combination SST89E516RD-40-I-PIE and SST89V516RD-33-I-PIE on page 78	Oct 2006
03	• Replaced FlashFlex51 with FlashFlex globally	Jan 2007
A	• Applied new document format • Released document under letter revision system • Updated spec number from S71273 to DS25093	Nov 2011
B	• Removed “Not recommended for new designs” statement on page 1.	Feb 2013

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